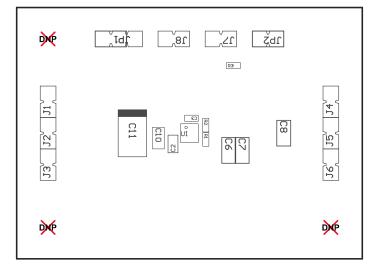
ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

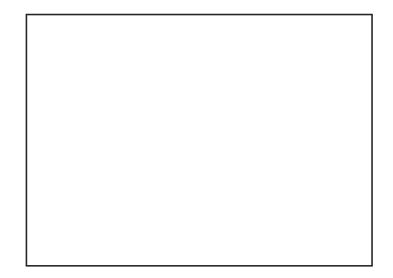
ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01457 REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-01457	
PLOT NAME = Top Assembly Drawing	GENERATED : 4/10/2017 10:13:57	' AM TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01457 REV: E1	SVN REV: Not In VersionControl
	TID #: TIDA-01457	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/10/2017 10:13:58	AM TEXAS INSTRUMENTS

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